Product Change Notification: CENO-03XUXP848

Date:

09-Sep-2026

Product Category:

Ethernet Bridges

Notification Subject:

CCB 6910.003 Final Notice: Qualification of MTAI as an additional assembly site for LAN7801T-I/9JX, LAN7801T-I/9JXVAO, LAN7801-I/9JXVAO, LAN7801T/9JX, LAN7801-I/9JX, LAN7801/9JX, LAN7800T-I/VSX, LAN7800T/VSX, LAN7800/VSX, LAX7080T/VSX, LAN7800-I/VSX and LAX7080T-I/VSX catalog part numbers (CPN) available in 64L and 48L VQFN (9x9x1.0mm and 6x6x0.9mm) packages.

Affected CPNs:

CENO-03XUXP848_Affected_CPN_09092026.pdf
CENO-03XUXP848_Affected_CPN_09092026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MTAI as an additional assembly site for LAN7801T-I/9JX, LAN7801T-I/9JXVAO, LAN7801-I/9JXVAO, LAN7801T/9JX, LAN7801-I/9JX, LAN7801/9JX, LAN7800T-I/VSX, LAN7800T/VSX, LAN7800/VSX, LAX7080T/VSX, LAN7800-I/VSX and LAX7080T-I/VSX catalog part numbers (CPN) available in 64L and 48L VQFN (9x9x1.0mm and 6x6x0.9mm) packages.

Pre and Post Summary Changes:

	Pre Change		**Post Change**			**Change**
Assembly Site	ASE Inc. (ASE)	Amkor Assembly & Test (Shanghai) Co.,	ASE Inc. (ASE)	Amkor Assembly & Test (Shanghai) Co.,	Microchip Technology	Yes

		LTD (ANAC)		LTD (ANAC)	Thailand (HQ) (MTAI)	
Wire Material	CuPdAu	CuPdAu	CuPdAu	CuPdAu	CuPdAu	No
Die Attach Material	EN-4900F (PFAS-free)	CRM-1085A (PFAS-free)	EN-4900F (PFAS-free)	CRM-1085A (PFAS-free)	QMI519 (PFAS-free)	Yes
Molding Compound Material	G631H	G631BQF	G631H	G631BQF	G700LTD	Yes
Lead-Frame Material	C194	C194	C194	C194	A194 *	No
Lead-Frame Paddle Size	*64L VQFN:* 287 x 287 mils *48L VQFN:* 185 x 185 mils	*64L VQFN:* 244 x 244 mils	*64L VQFN:* 287 x 287 mils *48L VQFN:* 185 x 185 mils	*64L VQFN:* 244 x 244 mils	*64L VQFN:* 244 x 244 mils *48L VQFN:*185 x 185 mils	Yes
Lead-Frame Drawing	See Pre and Post Change Summary attachment for Comparison.					

Note *: C194, A194 and CDA194 lead-frame materials are the same — it is only a Microchip internal labelling difference.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 October 2026 (date code: 2644)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	September 2026					October 2026				
Work Week	36	37	38	39	40	40	41	42	43	44
Qual Report Availability		x								
Final PCN Issue Date		x								
Estimated Implementation Date										x

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.
Note: This is a qualification by similarity (QBS) to CCB# 6910.

Revision History: September 09, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_CENO-03XUXP848-Qual Report_CCB 6910.pdf
PCN_CENO-03XUXP848_Pre and Post Change_Summary.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN):

LAN7801T-I/9JX

LAN7801T-I/9JXVAO

LAN7801-I/9JXVAO

LAN7801T/9JX

LAN7801-I/9JX

LAN7801/9JX

LAN7800T-I/VSX

LAN7800T/VSX

LAN7800/VSX

LAX7080T/VSX

LAN7800-I/VSX

LAX7080T-I/VSX

QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: CENO-03XUXP848

Date:
March 4, 2025

Qualification of MTAI as an additional assembly site for LAN7801T-I/9JX, LAN7801T-I/9JXVAO, LAN7801-I/9JXVAO, LAN7801T/9JX, LAN7801-I/9JX, LAN7801/9JX, LAN7800T-I/VSX, LAN7800T/VSX, LAN7800/VSX, LAX7080T/VSX, LAN7800-I/VSX and LAX7080T-I/VSX catalog part numbers (CPN) available in 64L and 48L VQFN (9x9x1.0mm and 6x6x0.9mm) packages.
This is a Q006 Grade 3 Qualification.

PACKAGE QUALIFICATION REPORT

Purpose	QQualification of MTAI as an additional assembly site for LAN7801T-I/9JX, LAN7801T-I/9JXVAO, LAN7801-I/9JXVAO, LAN7801T/9JX, LAN7801-I/9JX, LAN7801/9JX, LAN7800T-I/VSX, LAN7800T/VSX, LAN7800/VSX, LAX7080T/VSX, LAN7800-I/VSX and LAX7080T-I/VSX catalog part numbers (CPN) available in 64L and 48L VQFN (9x9x1.0mm and 6x6x0.9mm) packages. This is a Q006 Grade 3 Qualification.
CN	E000246496
QUAL ID	R2401317 Rev. A
MP CODE	STB071KDXC50
Part No.	USX5007C/KD
Bonding No.	BD-002245 Rev. 01
CCB No.	6910
Package	
Type	100L VQFN
Package size	12 x 12 x 0.9mm
Lead Frame	
Paddle size	323x323 mils
Material	EFTEC64
Surface	Ag signal ring plated on DAP
Process	Etched
Lead Lock	No
Part Number	10110011
Treatment	Roughening
Material	
Epoxy	QMI519
Wire	CuPdAu wire
Mold Compound	G700LTD
Plating Composition	Matte Sn

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PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI252600940.000	TC14924313854.200	2439YD7
MTAI252601144.000	TC14924313854.200	2439YT8
MTAI252601148.000	TC14924313854.200	2439YTK

Result [X] Pass [ ] Fail [ ] _____

100L VQFN (12x12x0.9mm) assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 3 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 3)	30°C/ 60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 (IPC/JEDEC J-STD-020E)	IPC/JEDEC J-STD-020E	135(0)	0/135	Pass	
<u>Precondition Prior Perform Reliability Tests</u> **(At MSL Level 3)**	**Electrical Test:** +25°C and 85°C System: LTX_D1X Bake 150°C, 24 hrs System: CHINEE 30°C/60%RH Moisture Soak 192 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243 **Electrical Test:** +25°C and 85°C System: LTX_D1X	JESD22-A113	693(0)	0/693 693 693 693 0/693	Pass Pass	Good Devices

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	**Stress Condition:** -55°C to +125°C, 500 Cycles System : VOTSCH	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C and 85°C System: LTX_D1X		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)		45 (0)	0/45	Pass	
	Stress Condition: -55°C to +125°C, 1000 Cycles System: VOTSCH			231		
	Electrical Test: +25°C and 85°C System: LTX_D1X		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)		45 (0)	0/45		

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
HAST	**Stress Condition:** +110°C/85%RH, 264 hrs. **Bias Volt:** PS1:1.32 Volts, PS3: 3.63 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)		45 (0)	0/45	Pass	
	Stress Condition: +110°C/85%RH, 528 hrs. **Bias Volt:** PS1:1.32 Volts, PS3:3.63 Volts System: HAST 6000X			231		
	Electrical Test: +25°C and 85°C System: LTX_D1X		231(0)	0/231	Pass	
	Bond Strength: Wire Pull (>3.00 grams) Bond Shear (>8.00 grams)		45 (0)	0/45	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
UNBIASED-HAST	**Stress Condition:** +110°C/85%RH, 264 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: LTX_D1X		231(0)	0/231	Pass	77 units / lot
High Temperature Storage Life	**Stress Condition:** Bake 150°C, 500 hrs System: CHINEE	JESD22-A103		135		45 units / lot
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	
	Stress Condition: Bake 150°C, 1000 hrs System: CHINEE			135		
	Electrical Test: +25°C and 85°C System: LTX_D1X		135(0)	0/135	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Bond Strength Data Assembly	Wire Pull (> 3.00 grams)	Mil. Std. 883-2011	30 (0) Wires	0/30	Pass	
	Bond Shear (>8.00 grams)	CDF-AEC-Q100-001	30 (0) Bonds	0/30	Pass	

CCB 6910.003
Pre and Post Change Summary
PCN #: CENO-03XUXP848

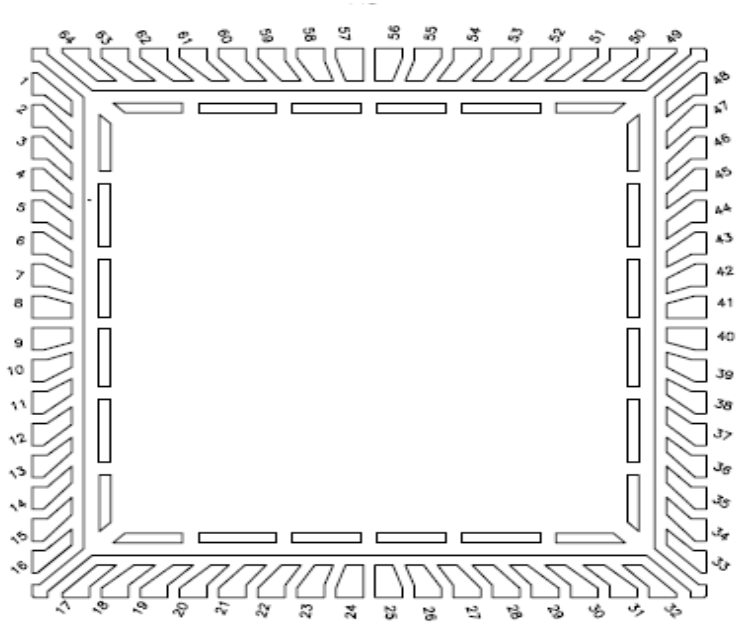


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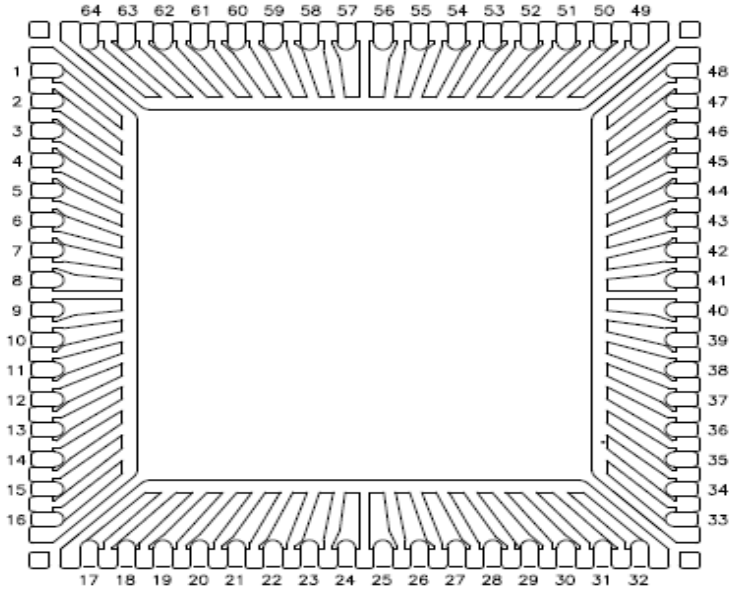
Lead Frame Comparison - *64L VQFN (9x9x1.0mm)*

ASE



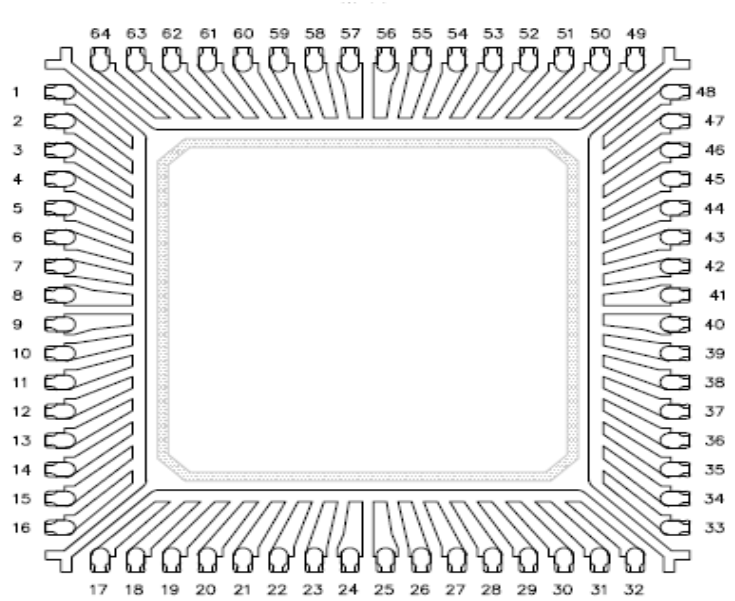
Lead-Frame Paddle Size	287 x 287
Lead-Frame Material	C194

ANAC



Lead-Frame Paddle Size	244 x 244
Lead-Frame Material	C194

MTAI



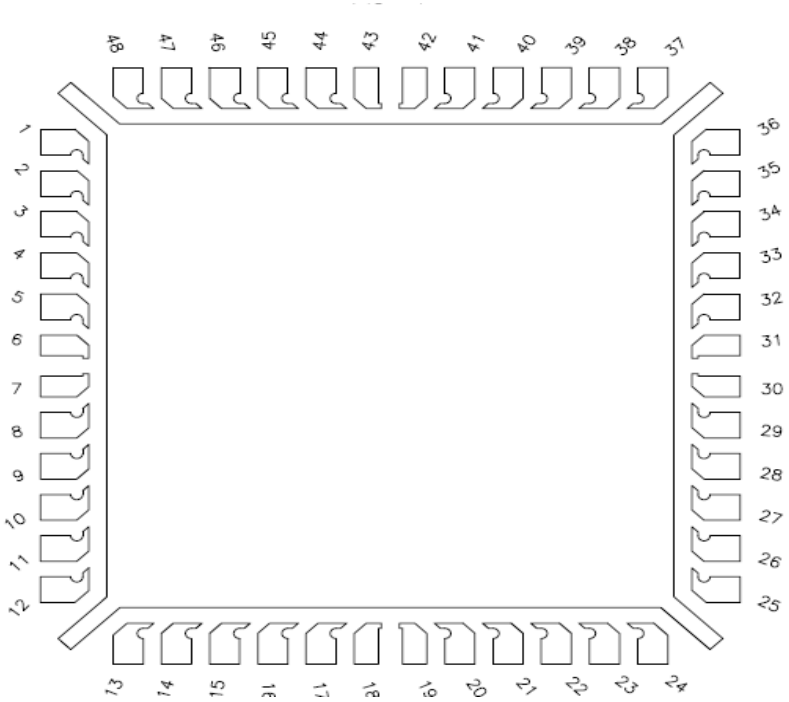
Lead-Frame Paddle Size	244 x 244
Lead-Frame Material	A194

Note 1: Not to scale
Note 2: C194, A194 and CDA194 lead-frame materials are the same — it is only a Microchip internal labelling difference.

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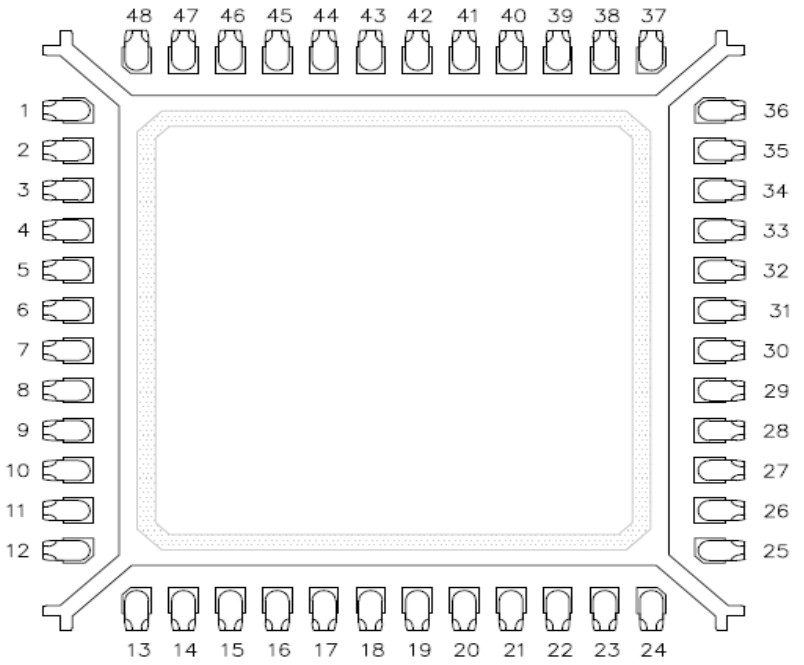
Lead Frame Comparison - *48L VQFN (6x6x0.9mm)*

ASE



Lead-Frame Paddle Size	185 x 185
Lead-Frame Material	C194

MTAI



Lead-Frame Paddle Size	185 x 185
Lead-Frame Material	A194

Note 1: Not to scale
Note 2: C194, A194 and CDA194 lead-frame materials are the same — it is only a Microchip internal labelling difference.

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